

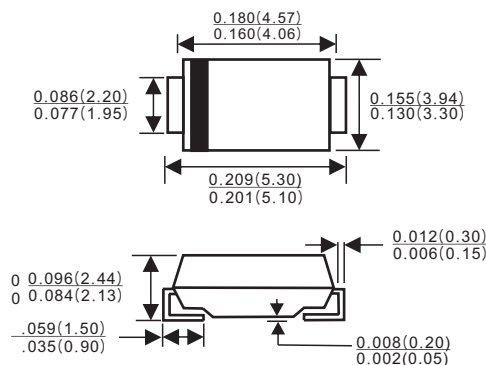


**REVERSE VOLTAGE: 50 - 1000 V**  
**FORWARD CURRENT: 1.0 A**

### Features

- ✧ Plastic package has underwriters laboratories flammability classification 94V-0
- ✧ For surface mount applications
- ✧ Glass passivated chip junctions
- ✧ Low profile package
- ✧ Easy pick and place
- ✧ Ultrafast recovery times for high efficiency
- ✧ Low forward voltage, low power loss
- ✧ Built-in strain relief, ideal for automated placement
- ✧ High temperature soldering:  
250°C/10 seconds on terminals

### SMB/DO-214AA



Dimensions in inches and (millimeters)

### Mechanical Data

- ✧ Case: JEDEC SMB, molded plastic body over passivated chip
- ✧ Polarity: Color band denotes cathode end
- ✧ Weight: 0.003 ounces, 0.093 gram

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

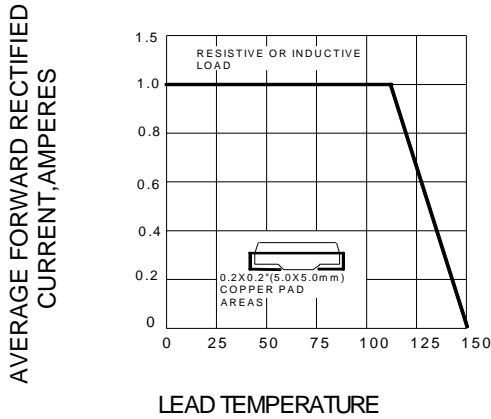
Parameter	Symbol	US1AB	US1BB	US1DB	US1GB	US1JB	US1KB	US1MB	UNITS
Marking code		US1A	US1B	US1D	US1G	US1J	US1K	US1M	
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RWS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=110^\circ\text{C}$	$I_{F(AV)}$	1.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	30.0							A
Maximum instantaneous forward voltage at 1.0A	$V_F$		1.0		1.3		1.7		V
Maximum DC reverse current @ $T_A=25^\circ\text{C}$ at rated DC blocking voltage @ $T_A=125^\circ\text{C}$	$I_R$				5.0				$\mu$
					100.0				
Maximum reverse recovery time at $I_F=0.5\text{A}$ $I_R=1.0\text{A}$ $I_{rr}=0.25\text{A}$	$t_{rr}$		50				75		ns
Typical junction capacitance at 4.0V, 1MHz	$C_J$		20				15		pF
Maximum thermal resistance (NOTE1)	$R_{JA}$ $R_{JL}$				55				$^\circ\text{C/W}$
					20				
Operating temperature range	$T_J$	-55----- +150							$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55----- +150							$^\circ\text{C}$

NOTE: 1.P.C.B.mounted on 0.2X0.2"(5.0X5.0mm) copper pad area

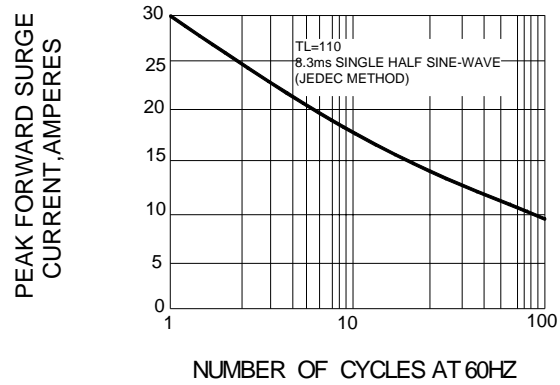


## Ratings AND Characteristic Curves

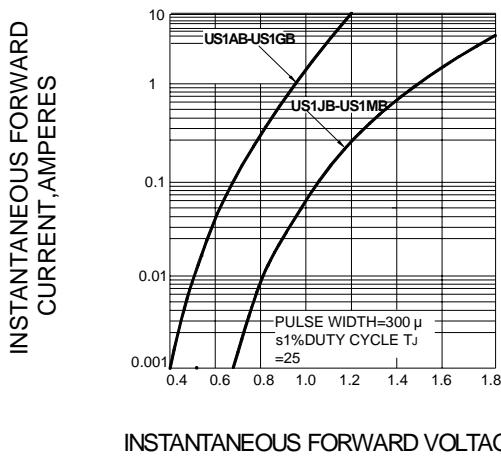
**FIG.1 – FORWARD CURRENT DERATING CURVE**



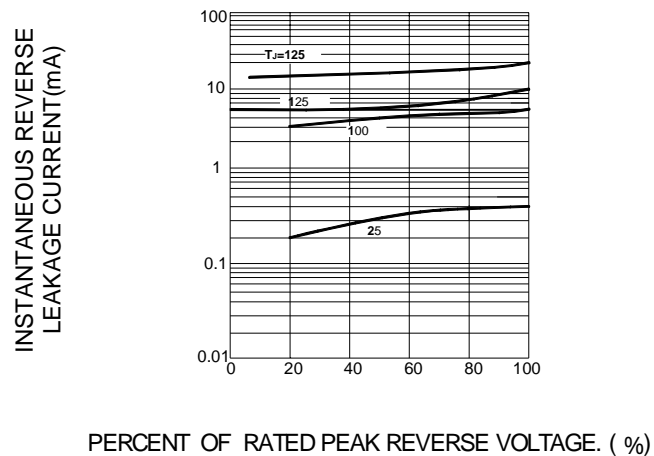
**FIG.2 – MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT**



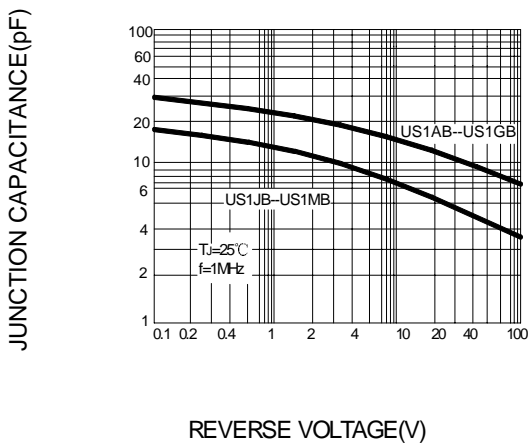
**FIG.3 – TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS**



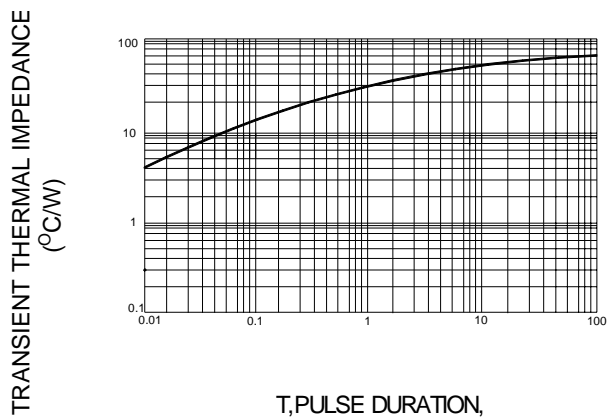
**FIG.4 – TYPICAL REVERSE CHARACTERISTICS**



**FIG.5 – TYPICAL JUNCTION CAPACITANCE**



**FIG.6 – TYPICAL TRANSIENT THERMAL IMPEDANCE**



PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
SMB	3000/REEL	48000	36X35.8X36.5	12.00	11.00